MA4J1130G

Silicon epitaxial planar type

For high speed switching circuits

■ Overview

MA4J1130G is optimal for general circuit supplies.

■ Features

- Optimum for high-density mounting
- Ensuring the forward current (Average) capacity $I_{F(AV)}$ = 200 mA
- High breakdown voltage: V_R = 80 V

■ Package

- Code
  SMini4-F2
- Pin Name
  1: Anode 3: Cathode
  2: Anode 4: Cathode

■ Marking Symbol: MA

■ Absolute Maximum Ratings T_a = 25°C

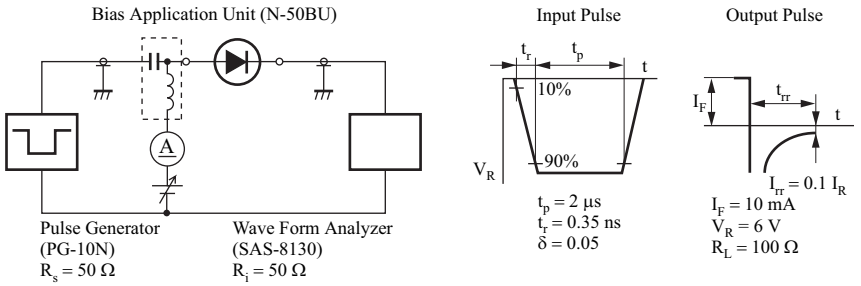
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	80	V
Maximum peak reverse voltage	V_{RM}	80	V
Forward current (Average) *1	$I_{F(AV)}$	200	mA
Peak forward current	I_{FM}	600	mA
Non-repetitive peak forward surge current *2	I_{FSM}	1	A
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	–55 to +150	°C

Note) *1: $I_{F(AV)}$ = 200 mA achieved with a printed circuit board.
*2: t = 1 s

■ Electrical Characteristics T_a = 25°C±3°C

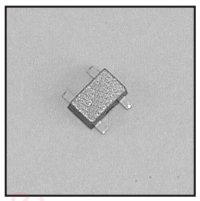
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	I_F = 200 mA			1.1	V
Reverse current	I_{R1}	V_R = 15 V			50	nA
	I_{R2}	V_R = 75 V			500	nA
	I_{R3}	V_R = 75 V, T_a = 100°C			100	µA
Terminal capacitance	C_t	V_R = 10 V, f = 1 MHz			4	pF
Reverse recovery time *	t_{rr}	I_F = 10 mA, V_R = 6 V I_{rr} = 0.1 I_R , R_L = 100 Ω			10	ns

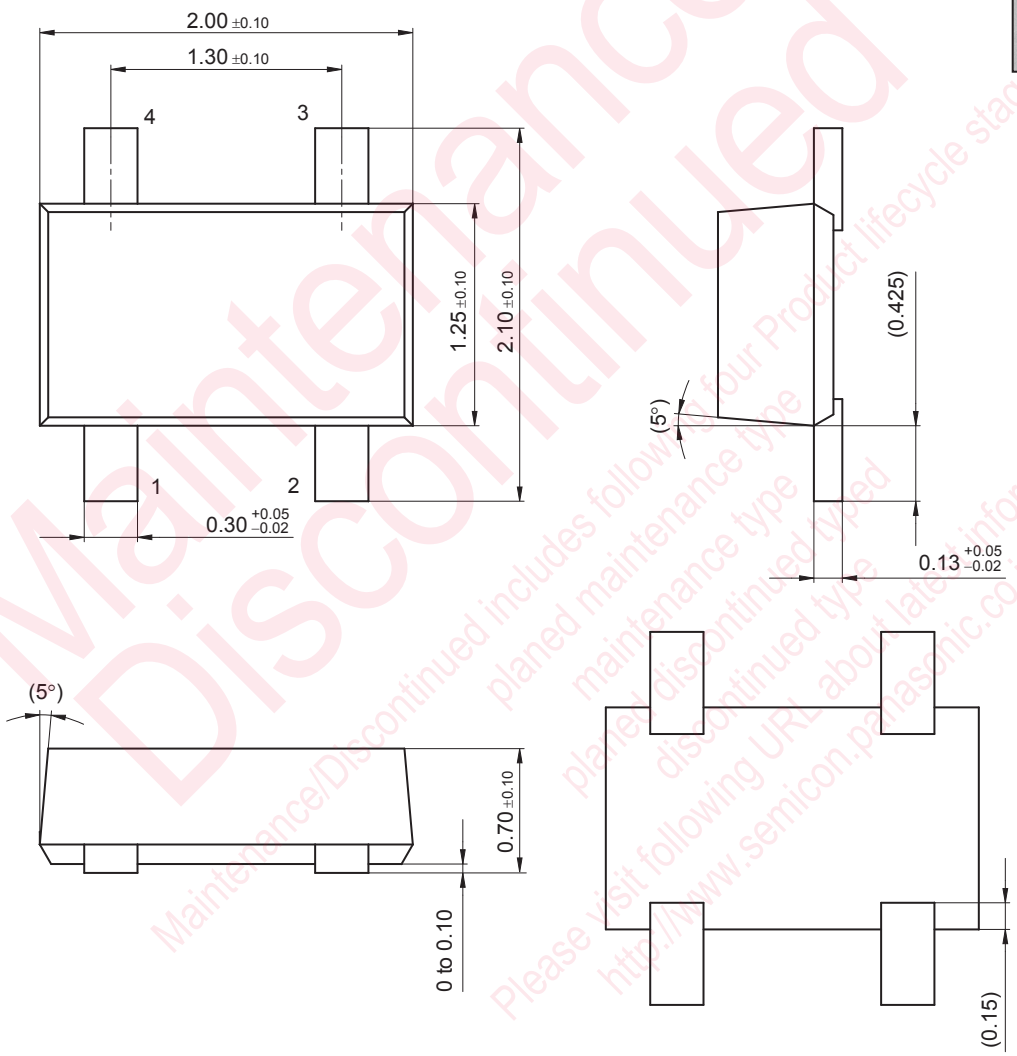
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. Absolute frequency of input and output is 100 MHz
3. *: t_{rr} measurement circuit



SMini4-F2

Unit: mm





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